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(54) Title: A PRIMER COMPOSITION

(57) Abstract: A primer coating composition for a metal substrate is described. The primer has a suitable binder and is characterised in that there is at least one semiconductor photocatalyst dispersed throughout the primer coating composition. A process of coating a metal substrate is also described. The invention extends to the use of a semiconductor photocatalyst as a top-coat to primer adhesion promoter or as a primer to top-coat delamination inhibitor in a primer coating composition.